

Title (en)  
Flux

Title (de)  
Flussmittel

Title (fr)  
Flux

Publication  
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Application  
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Priority  
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Abstract (en)  
[origin: US5980650A] A flux which contains irreversibly dehydrated K<sub>2</sub>AlF<sub>5</sub>, for soldering light metal materials, in particular aluminum. The flux has the advantages of forming a very uniform flux coating on the workpiece or workpieces to be soldered and exhibiting outstanding flow of the solder. An appropriate soldering process, an aqueous flux suspension and preparation processes for the flux are also disclosed.

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IPC 8 full level  
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